



[TuB2] Sustainable Etch

Session Date	November 11 (Tue.), 2025
Session Time	14:50–16:05
Session Room	Room B (Grand Ballroom 1, 2F)
Session Chair	Dr. Thorsten Lill (Lam Research, USA)

[TuB2-1] [Invited]

14:50–15:20

Low-GWP Cyclic Etching of SiO₂ Contact Holes Using Heptafluoropropyl Methyl Ether

Sanghyun You and Chang-Koo Kim (Ajou Univ., Korea)

[TuB2-2]

15:20–15:35

Low Global Warming C₅F₁₀O/H₂O Plasma for Low Temperature Etching of SiO₂ and Si₃N₄

Daeun Hong, Sumin Park, Eunsu Lee, and Heeyeop Chae (Sungkyunkwan Univ., Korea)

[TuB2-3]

15:35–15:50

Comparative Study of C₃F₆ and CF₄ for Sustainable Plasma Etching of SiO₂

Inkyoung Cho and Chang-Koo Kim (Ajou Univ., Korea)

[TuB2-4]

15:50–16:05

Comparison of Etching Characteristics and Environmental Impact of Fluorocarbon Isomers in High Aspect Ratio (HAR) Etching Processes

Seyoung Choi, Chanhyuk Choi, Myeongho Park, Junsoo Lee, Akihide Sato, Sungtaek Kim, Dongwoo Kim, and Geunyoung Yeom (Sungkyunkwan Univ., Korea)